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PATENT
TESSERA 3.0-115 CONT CIP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of :
Fjelstad :
: Group Art Unit:
Application No. 09/766,814 :
: Examiner: Not Assigned
Filed: January 22, 2001 :
: Date: March 23, 2001
For: MICROELECTRONIC PACKAGES :
HAVING DEFORMED LEADS AND:
METHODS THEREFOR X

Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to an action on the merits, please amend the
above-identified application as follows:

Please add new claims 52-74 as follows:

Please add the following new claims:

52. (New) A method of making a microelectronic
assembly comprising:

(a) providing a connection component having a
first surface including conductive leads and contacts, said
conductive leads having terminal ends permanently secured to said
connection component and tip ends releasably secured to said
connection component;

I hereby certify that this correspondence is being deposited
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First Class mail in an envelope addressed to Commissioner for
Patents, Washington, D.C. 20231 on March 23, 2001.

Michael J. Doherty
(Signature)

MICHAEL J. DOHERTY

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